

# $P^+$ implantation and annealing effects on the $T_c$ in BiSrCaCuO films

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The  $T_c$  changes related to the microstructure as a function of annealing temperature for the BiSrCaCuO (BSCCO) film implanted with 170 keV  $P^+$  at two different doses were studied. The BSCCO films were prepared by d.c. sputtering on MgO substrates. For the film implanted at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$  post-implantation annealing at 600–800 °C enabled the  $T_c$ s of the film to be completely recovered. For the film implanted at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$  the  $T_c$ s were only partly recovered after 600 °C annealing. On further annealing at 700 °C the superconductivity of the film disappeared. TEM examination showed that significant amount of CaP,  $\text{Ca}_3\text{P}_2$ , and some unknown phases were formed. It is considered that the significant amounts of these phases formed during post-implantation annealing renders the recovery of the superconductivity of the  $P^+$ -implanted BSCCO film difficult.

## 1. Introduction

Radiation effects on the superconducting properties of the YBaCuO and BiSrCaCuO (BSCCO) systems have been extensively studied in both fundamental and technological research [1–7]. In general,  $T_c$  is reduced as the radiation dose is increased. A quantum interference device fabricated on YBaCuO thin film using the patterning by oxygen or arsenic ion implantations has been reported [8]. It is well known that ion-implantation techniques have been applied to the fabrication of semiconductor devices. In view of the possible application of superconducting thin films in microelectronic devices [9] it is interesting to investigate the ion-implantation effect on the superconductivity of the high  $T_c$  films. In our previous results,  $B^+$  implantation and annealing effects on the superconductivity and microstructure of the BSCCO film were studied [10]. It seems that the  $B^+$  implantation technique is compatible with the BSCCO film in device application. In this work the  $T_c$  changes related to the microstructure as a function of the annealing temperature in the  $P^+$ -implanted BSCCO film were studied.

## 2. Experimental procedure

BSCCO films were deposited on (1 0 0) MgO substrate in 0.05 torr (1 torr = 133.322 Pa) of argon by d.c. sputtering from a sintered  $\text{Bi}_2\text{Sr}_2\text{CaCu}_3\text{O}_x$  target. The target–substrate distance and plasma power were 3 cm and 50 W, respectively. During sputtering, the substrate temperature was kept at about 200 °C. The thickness of the as-deposited film was around 2  $\mu\text{m}$ . After appropriate annealing, the as-deposited films became superconducting [11, 12]. The temperature dependence of the electrical resistance was measured by the four-probe method. Ion-implantation was per-

formed at room temperature by 170 keV  $P^+$ , and with a beam current of 2  $\mu\text{A}$ . The microstructure of the film was observed using transmission electron microscopy (TEM). The post-implantation annealing time for each thermal treatment was 15 min.

## 3. Results and discussion

### 3.1. $5.0 \times 10^{15} \text{ cm}^{-2}$

For Sample A with the chemical compositions Bi: Sr: Ca: Cu = 30:24:16:30 the  $T_c$  (onset) and  $T_c$  (zero) were around 87 and 79 K, respectively. After being implanted with 170 keV  $P^+$  at a dose of  $5.0 \times 10^{15} \text{ cm}^{-2}$  the  $T_c$ s of the film became 85 and 77 K, respectively, which were somewhat lower than those prior to ion implantation. Fig. 1 shows the  $P^+$  implantation and annealing effects on the  $T_c$ s of the film. The penetration depth of the 170 keV  $P^+$  in the BSCCO film was estimated to be about 0.15  $\mu\text{m}$  using TRIM-90 code [13]. From TEM examination, amorphous zones were formed in the 2 2 1 2 grains due to ion implantation and most of the film still remained crystalline. One example is shown in Fig. 2. It is evident that the implantation-induced defects, such as the amorphous zones, produce a significant decrease in carrier mobility, resulting in the degradation of superconductivity of the film. After annealing at 600 °C the  $T_c$ s of the film were recovered to its original values before ion implantation, meanwhile the amorphous zones were recrystallized to the 2 2 1 2 phase as shown in Fig. 3. On annealing at 800 °C the  $T_c$ s of the film still remained unchanged, indicating that phosphorus dopants at the level of  $5 \times 10^{15} \text{ cm}^{-2}$  have no significant effect on the  $T_c$  of the annealed film. A similar result was also observed in the  $B^+$ -implanted BSCCO films after 800 °C annealing, in

which the boron dopants resident in the film were  $3.7 \times 10^{15} \text{ cm}^{-2}$  [10].

### 3.2. $1.0 \times 10^{17} \text{ cm}^{-2}$

For Sample B with the chemical compositions

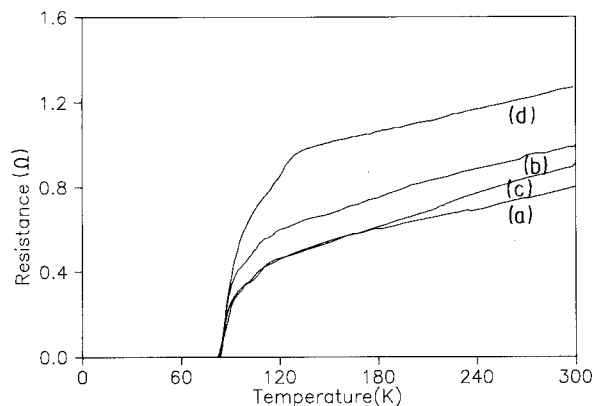


Figure 1 Resistance-temperature curves for the film implanted with 170 keV  $\text{P}^+$  at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$ . (a) As-prepared, (b) as-implanted, (c) post-implantation annealing at 600 °C, (d) post-implantation annealing at 800 °C.

$\text{Bi}:\text{Sr}:\text{Ca}:\text{Cu} = 23:30:16:31$ , the  $T_c$  (onset) and  $T_c$  (zero) were 85 and 72 K, respectively. After being implanted with 170 keV  $\text{P}^+$  at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$ , the film was annealed starting from 500 °C. The changes in the resistance-temperature ( $R-T$ ) curves are shown in Fig. 4. The  $R-T$  curve of the as-implanted film showed semiconductor behaviour. From TEM examination, the fraction of amorphous regions was larger than that in the film implanted at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$ . After 600 °C annealing, the  $T_c$  (onset) of the implanted film was significantly recovered but there was still residual resistance of about 14 mΩ below 70 K. It is worth noting that as the annealing temperature reached 700 °C the  $R-T$  curve of the film showed semiconductor behaviour again. These results are greatly different from those for Sample A implanted at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$ , in which post-implantation annealing at 600–800 °C enables the  $T_c$ s of the film to be completely recovered to the values prior to ion implantation.

It has been reported that phosphorus dopants have a tendency to decompose the 2223 and 2212 phases to the 2201 and non-superconducting phases after

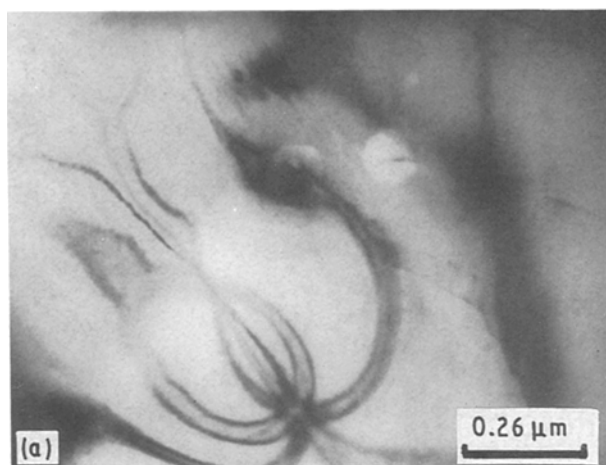


Figure 2 (a) Bright-field image of the film implanted with 170 keV  $\text{P}^+$  at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$  showing that the amorphous zones were formed in the 2212 grain. (b) Diffraction pattern of (a).

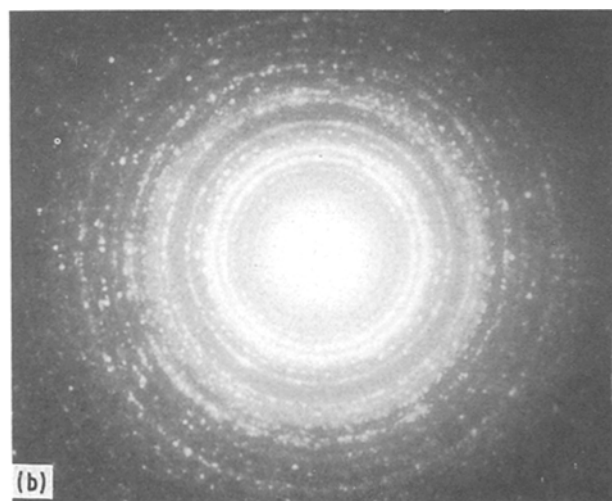
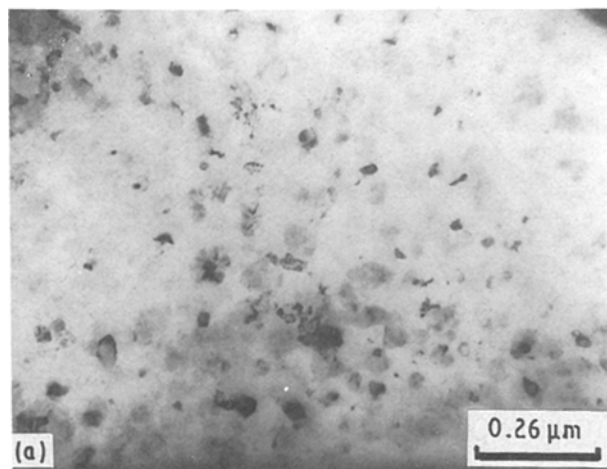


Figure 3 (a) Bright-field image of the film annealed at 600 °C after having been implanted with 170 keV  $\text{P}^+$  at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$  showing the recrystallization of the 2212 phase from the amorphous zones. (b) Diffraction pattern of (a).

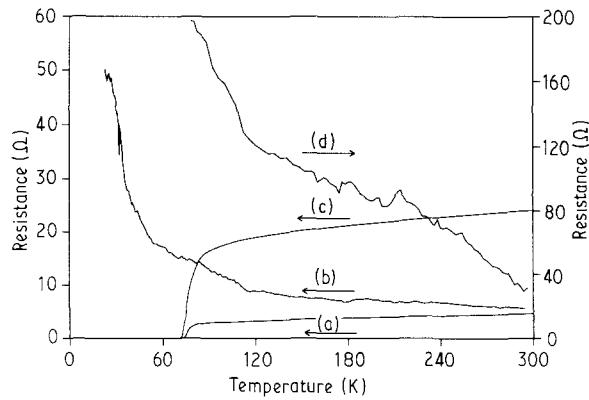


Figure 4 Resistance-temperature curves for the film implanted with 170 keV  $P^+$  at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$ . (a) As-prepared, (b) as-implanted, (c) post-implantation annealing at 600 °C, (d) post-implantation annealing at 700 °C.

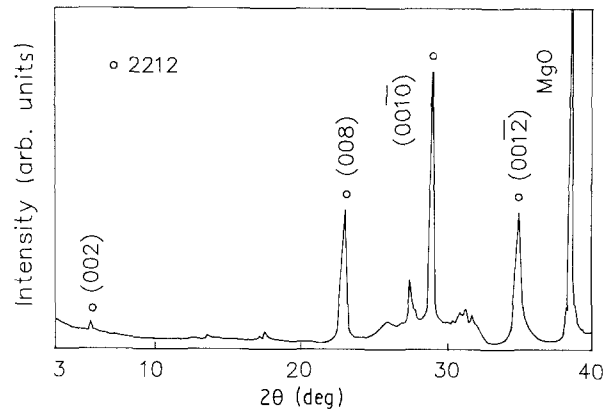


Figure 5 X-ray diffraction pattern showing that for the BSCCO film annealed at 700 °C after having been implanted with 170 keV  $P^+$  at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$ , no significant amount of the 2201 phase was formed.

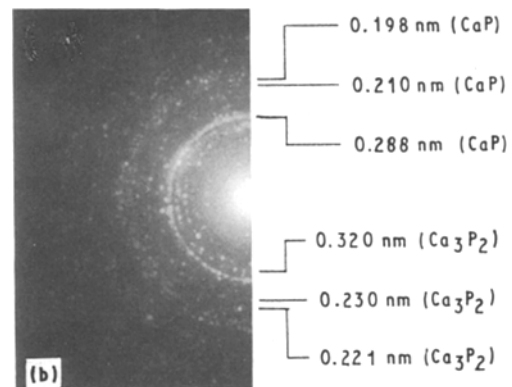
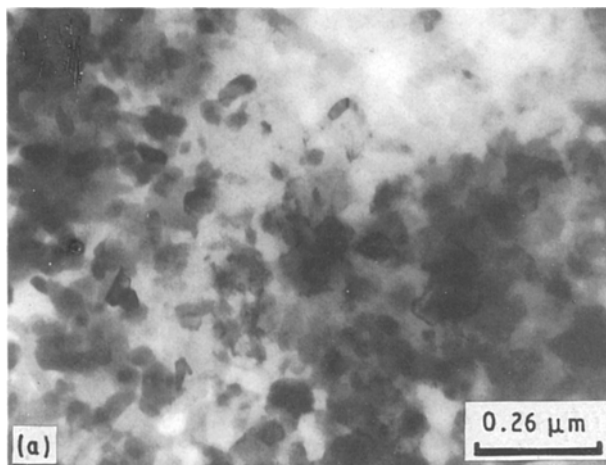


Figure 6 (a) Bright-field image showing that significant amount of CaP,  $Ca_3P_2$ , and unknown phases were formed in the film annealed above 600 °C after having been implanted with 170 keV  $P^+$  at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$ . (b) Diffraction pattern of (a).

860 °C annealing [14]. In this study, for the film annealed at 600 and 700 °C after having been implanted with 170 keV  $P^+$  at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$ , no significant amount of the 2201 phase was formed, as seen from X-ray diffraction analysis in Fig. 5, while from TEM examination, a significant amount of CaP,  $Ca_3P_2$ , and some unknown phases were observed, as seen in Fig. 6. It is evident that the formation of these phases during post-implantation annealing plays an important role in degrading the superconductivity of the film. The degradation of the superconductivity due to the implantation-induced compounds was also observed in the  $H^+$ -implanted  $YBa_2Cu_3O_x$  (123) superconductor, in which  $H^+$  deoxidized the 123 compound to form  $H_2O$  which reacted with 123 compound to form  $Y_2BaCuO_5$  and CuO [15].

#### 4. Conclusion

For the BSCCO film implanted with 170 keV  $P^+$  at a dose of  $5 \times 10^{15} \text{ cm}^{-2}$  post-implantation annealing at 600–800 °C enabled the  $T_c$ s of the film to be completely recovered to their original values prior to ion implantation. For the BSCCO film implanted with

170 keV  $P^+$  at a dose of  $1.0 \times 10^{17} \text{ cm}^{-2}$ , the  $T_c$ s were only partly recovered after 600 °C annealing, there still being a residual resistance of 14 mΩ below 70 K. On further annealing at 700 °C the superconductivity of the film disappeared. From TEM examination, significant amounts of CaP,  $Ca_3P_2$ , and some unknown phases were formed. It is considered that significant amounts of these phases formed during post-implantation annealing renders the recovery of the superconductivity of the  $P^+$ -implanted BSCCO films difficult.

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